

AMENDMENT

In The Claims:

Please amend the claims as follows:

1. (previously presented) A camera module, comprising:
a lens;
a holder having a lower portion, said holder holding said lens;
at least a flexible circuit board, said flexible circuit board including a first flexible circuit board and a second flexible circuit board;
an image sensing and processing unit including an image sensing device and an optional signal processing device stacked on and electrically connected to said image sensing device, said image sensing and processing unit being packaged on one side of said flexible circuit board, and said signal processing device electrically connected to the first flexible circuit board and said image sensing device electrically connected to the second flexible circuit board;
wherein said holder is fixed on said flexible circuit board, said image sensing and processing unit inside said lower portion of said holder; and
a hard plate disposed on the other side of said flexible circuit board corresponding to said image sensing and processing unit.
2. (original) The camera module of claim 1, further comprising a glass layer directly covering said image sensing device.

Claims 3 and 4 (canceled)

5. (original) The camera module of claim 1, wherein said image sensing device is a CMOS image sensing device.

6. (original) The camera module of claim 1, wherein said signal processing device includes a digital signal processing chip.

7. (original) The camera module of claim 1, wherein said signal processing device and said image sensing device are electrically connected together by wire bonding.

8. (previously presented) A camera module, comprising:

a lens;

a holder having a lower portion and a bottom, said holder holding said lens;

an image sensing and processing unit including an image sensing device and an optional signal processing device stacked on and electrically connected to said image sensing device;

a plate holding said image sensing and processing unit and covering said bottom of said holder, said image sensing and processing unit being inside said lower portion of said holder; and

at least a flexible circuit board directly connected to said image sensing and processing unit, wherein said flexible circuit board includes a first flexible circuit board electrically connected to said signal processing device and a second flexible circuit board electrically connected to said image sensing device.

9. (original) The camera module of claim 8, further comprising a glass layer directly covering said image sensing device.

Claims 10 and 11 (canceled)

12. (previously presented) The camera module of claim 8, wherein a viscous layer is between said first flexible circuit board and said second flexible circuit board

13. (original) The camera module of claim 8, wherein said plate includes a plastic plate.

14. (original) The camera module of claim 8, wherein said image sensing device is a CMOS image sensing device.

15. (original) The camera module of claim 8, wherein said signal processing device includes a digital signal processing chip.

16. (original) The camera module of claim 8, wherein said signal processing device and said image sensing device are electrically connected together by wire bonding.

17. (currently amended) A image sensing and processing unit, comprising:
a signal processing device;
an image sensing device ~~stacked on and~~ electrically connected to signal processing device,

wherein the image sensing device is directly stacked on the signal processing device such that the image sensing device contacts with the signal processing device; and

a circuit board including a first flexible circuit board electrically connected to said signal processing device and a second flexible circuit board electrically connected to said image sensing device.

18. (currently amended) The unit of claim 17, wherein ~~said circuit board includes a flexible circuit board, and~~ said image sensing device is disposed on said second flexible circuit board.

Claims 19 and 20 (canceled)